

## 1 ABSTRACT OF THE DISCLOSURE

2 We have discovered a method of reducing the effect of material sputtered/etched  
3 during the preheating of a substrate. One embodiment of the method pertains to preheating  
4 a substrate which includes a metal-containing layer which is to be pattern etched subsequent  
5 to preheating. The method includes exposing the substrate to a preheating plasma which  
6 produces a deposit or residue during preheating which is more easily etched than said metal-  
7 containing layer during the subsequent plasma etching of said metal-containing layer.